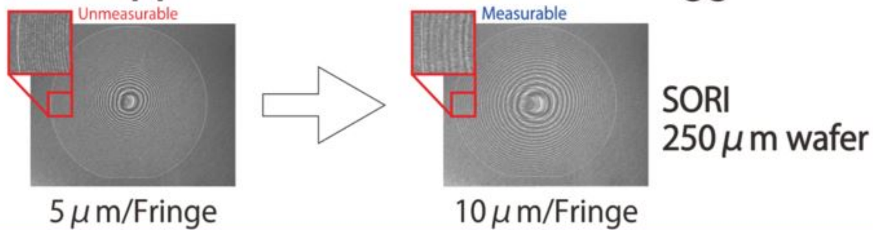
Slanting incidence interference method Flatness Tester

Applicable to flatness measurement of Silicon Carbide and Related Materials

Now developing!

Applied even if the wafer has bigger bow.



5 μm/Fringe 10 μm/Fringe

SORI 250 μm wafer

The dynamic range will be extended in the near future.

Advantages

- Original phase shift method is adopted for analyzing multiple interference fringes
- Calibration by the user is unnecessary
- The measured results can be displayed in various formats including measured values, contour line map, bird's eye view, and cross-section view.

Applications

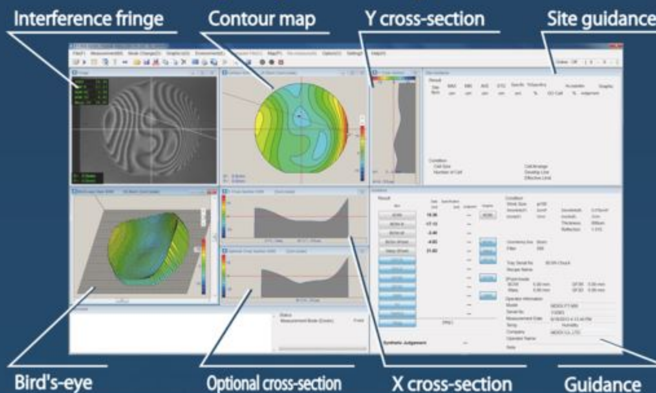
- Measurement and analysis of flatness for silicon, oxide, compound such as SiC and glass wafer, metallic piece, aluminum and glass disk and parts of machine, etc.
- Transparent samples (Sapphire,Crystal,Glass) can be measured by minimizing the amount of rear surface interference.
- Shape management before and after wafer processing and epitaxial growth of the wafer, Measurement of the bonded wafer.

Measurement Substrate Example

Applicable to wafers (silicon, compound, oxide or glass), metallic fragments, disks (aluminum or glass), or user-defined shaped parts, etc.

Screen Display Examples

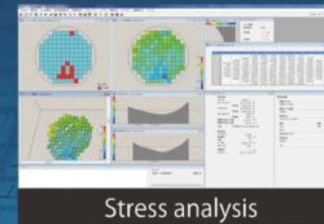
Interference fringe | Contour map | Y cross-section | Site guidance



Bird's-eye | Optional cross-section | X cross-section | Guidance

SORI、BOW、Warp

GBIR (TTV)、SBIR (LTV)



Stress analysis

FT-17

Applicable up to φ 130 mm outer diameter

FT-900

Applicable up to φ 200 mm outer diameter

Fully automated Flatness Tester

Automatic conveyor models are provided by Kobelco Research Institute, Inc.